



Material Content Data Sheet



Sales Product Name	BTS7811K			Issued		29. August 2013		
MA#	MA000074202							
Package	P-TO263-15-1			Weight*		3397.51 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.367	0.51	0.51	5112	5112
leadframe	non noble metal	iron	7439-89-6	2.037	0.06		600	
	inorganic material	phosphorus	7723-14-0	0.611	0.02		180	
	non noble metal	copper	7440-50-8	2034.173	59.88	59.96	598724	599505
wire	non noble metal	aluminium	7429-90-5	1.824	0.05	0.05	537	537
encapsulation	organic material	carbon black	1333-86-4	19.717	0.58		5803	
	plastics	epoxy resin	-	216.884	6.38		63836	
	inorganic material	silicondioxide	60676-86-0	1077.850	31.72	38.68	317247	386886
leadfinish	non noble metal	lead	7439-92-1	3.913	0.12		1152	
	non noble metal	tin	7440-31-5	9.939	0.29	0.41	2925	4077
plating	non noble metal	nickel	7440-02-0	0.493	0.01		145	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	145
solder	noble metal	silver	7440-22-4	0.317	0.01		93	
	non noble metal	tin	7440-31-5	0.254	0.01		75	
	non noble metal	lead	7439-92-1	12.128	0.36	0.38	3570	3738
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com